SOD64

hermetically sealed glass package; axial leaded; 2 leads 23 October 2018 Package information

1 Package summary

Terminal position code A (axial)

Package type descriptive code GALF2

Package type industry code GALF2

Package style descriptive code LALF (glass axial (leaded) long form)

Package body material type L (glass)

Mounting method type T (through-hole mount)

Issue date 14-10-1997
Manufacturer package code SOD64

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package diameter	-	4.5	-	mm
actual quantity of termination	_	2	-	



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2 Package outline

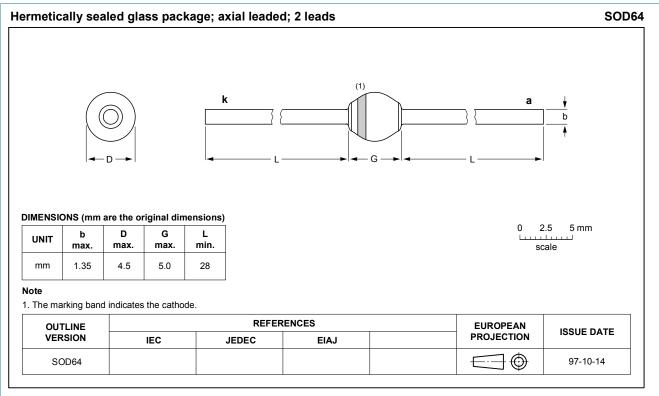


Figure 1. Package outline GALF2 (SOD64)

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3 Legal information

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